

CLAIMS:

- Sub A1
1. An electrically conductive silicone rubber composition having improved adhesion, comprising
- 5 (A) 100 parts by weight of an organopolysiloxane having at least two aliphatic unsaturated groups in a molecule,
- (B) 0.1 to 100 parts by weight of finely divided silica,
- (C) 30 to 700 parts by weight of a metal powder or an electrically conductive metal-plated powder,
- 10 (D) 0.1 to 20 parts by weight of an adhesive aid, and
- (E) a curing agent in an amount sufficient to cure the organopolysiloxane.
2. The silicone rubber composition of claim 1, wherein
- 15 the metal powder of component (C) is a silver powder.
3. The silicone rubber composition of claim 1, wherein component (C) is a metal-plated silica powder having a construction comprising silica covered with a nickel layer
- 20 which in turn is covered with a gold layer.
4. The silicone rubber composition of claim 1, wherein component (D) is a compound having at least one alkoxy group or epoxy group or both in a molecule.
- 25 5. The silicone rubber composition of claim 1, wherein component (D) is an organosilicon compound having in a molecule at least two different groups selected from the class consisting of SiH, epoxy, alkoxy and alkenyloxy groups.
- 30 6. The silicone rubber composition of claim 1, wherein component (D) is an organosilicon compound having in a molecule at least one SiH group and at least one group containing an aromatic ring and/or a carbonyl group.
- 35 7. The silicone rubber composition of claim 1, wherein the curing agent (E) is an organic peroxide.

8. The silicone rubber composition of claim 1, wherein the curing agent (E) is an addition reaction-type curing agent comprising an organohydrogenpolysiloxane having at least two SiH groups in a molecule and a platinum group

5 metal catalyst.

9. An article comprising a substrate of a metal or resin and a coating of the conductive silicone rubber composition of claim 1 applied and cured to the substrate without a

10 primer, the cured coating of the composition being
integrated with the substrate.

Add A2

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